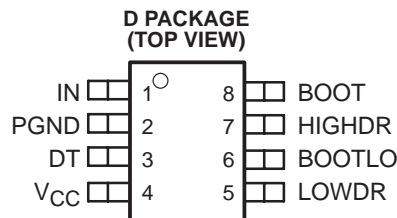


TPS2832, TPS2833 FAST SYNCHRONOUS-BUCK MOSFET DRIVERS WITH DEAD-TIME CONTROL

SLVS195C – FEBRUARY 1999 – REVISED JANUARY 2001

- Floating Bootstrap or Ground-Reference High-Side Driver
- Adaptive Dead-Time Control
- 50-ns Max Rise/Fall Times and 100-ns Max Propagation Delay – 3.3-nF Load
- Ideal for High-Current Single or Multiphase Power Supplies
- 2.4-A Typical Peak Output Current
- 4.5-V to 15-V Supply Voltage Range
- Internal Schottky Bootstrap Diode
- Low Supply Current...3-mA Typical
- –40°C to 125°C Operating Virtual Junction Temperature
- Available in SOIC Package



description

The TPS2832 and TPS2833 are MOSFET drivers for synchronous-buck power stages. These devices are ideal for designing a high-performance power supply using switching controllers that do not have MOSFET drivers. The drivers are designed to deliver 2.4-A peak currents into large capacitive loads. The high-side driver can be configured as a ground-reference driver or as a floating bootstrap driver. An adaptive dead-time control circuit eliminates shoot-through currents through the main power FETs during switching transitions and provides high efficiency for the buck regulator.

The TPS2832 has a noninverting input. The TPS2833 has an inverting input. The TPS2832/33 drivers, available in 8-terminal SOIC packages, operate over a junction temperature range of –40°C to 125°C.

AVAILABLE OPTIONS

T_J	PACKAGED DEVICES
	SOIC (D)
–40°C to 125°C	TPS2832D TPS2833D

The D package is available taped and reeled. Add R suffix to device type (e.g., TPS2832DR)

Related Synchronous MOSFET Drivers

DEVICE NAME	ADDITIONAL FEATURES	INPUTS	
TPS2830	ENABLE, SYNC and CROWBAR	CMOS	Noninverted
TPS2831			Inverted
TPS2834	ENABLE, SYNC and CROWBAR	TTL	Noninverted
TPS2835			Inverted
TPS2836	W/O ENABLE, SYNC and CROWBAR	TTL	Noninverted
TPS2837			Inverted



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



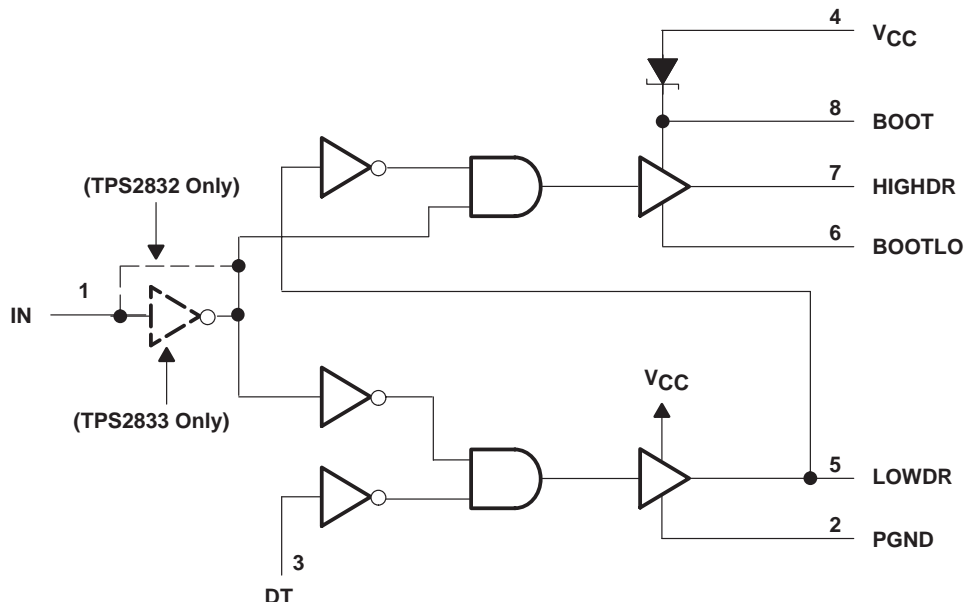
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TPS2832, TPS2833 FAST SYNCHRONOUS-BUCK MOSFET DRIVERS WITH DEAD-TIME CONTROL

SLVS195C – FEBRUARY 1999 – REVISED JANUARY 2001

functional block diagram



Terminal Functions

TERMINAL NAME	TERMINAL NO.	I/O	DESCRIPTION
BOOT	8	I	Bootstrap terminal. A ceramic capacitor is connected between BOOT and BOOTLO terminals to develop the floating bootstrap voltage for the high-side MOSFET. The capacitor value is typically between 0.1 μ F and 1 μ F. A 1-M Ω resistor should be connected across the bootstrap capacitor to provide a discharge path when the driver has been powered down.
BOOTLO	6	O	This terminal connects to the junction of the high-side and low-side MOSFETs.
DT	3	I	Dead-time control terminal. Connect DT to the junction of the high-side and low-side MOSFETs
HIGHDR	7	O	Output drive for the high-side power MOSFET
IN	1	I	Input signal to the MOSFET drivers (noninverting input for the TPS2832; inverting input for the TPS2833).
LOWDR	5	O	Output drive for the low-side power MOSFET
PGND	2		Power ground. Connect to the FET power ground.
VCC	4	I	Input supply. Recommended that a 1 μ F capacitor be connected from VCC to PGND.

detailed description

low-side driver

The low-side driver is designed to drive low $R_{ds(on)}$ N-channel MOSFETs. The current rating of the driver is 2 A, source and sink.

high-side driver

The high-side driver is designed to drive low $R_{ds(on)}$ N-channel MOSFETs. The current rating of the driver is 2 A, source and sink. The high-side driver can be configured as a ground-reference driver or a floating bootstrap driver. The internal bootstrap diode, is a Schottky for improved drive efficiency. The maximum voltage that can be applied between the BOOT terminal and ground is 30 V.

dead-time (DT) control†

Dead-time control prevents shoot through current from flowing through the main power FETs during switching transitions by controlling the turn-on times of the MOSFET drivers. The high-side driver is not allowed to turn on until the gate drive voltage to the low-side FET is low, and the low-side driver is not allowed to turn on until the voltage at the junction of the power FETs (V_{drain}) is low; the DT terminal connects to the junction of the power FETs.

IN†

The IN terminal is a digital terminal that is the input control signal for the drivers. The TPS2832 has a noninverting input; the TPS2833 has an inverting input.

†High-level input voltages on IN and DT must be greater than or equal to $0.7V_{CC}$.

TPS2832, TPS2833 FAST SYNCHRONOUS-BUCK MOSFET DRIVERS WITH DEAD-TIME CONTROL

SLVS195C – FEBRUARY 1999 – REVISED JANUARY 2001

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V_{CC} (see Note 1)	–0.3 V to 16 V
Input voltage range: BOOT to PGND (high-side driver ON)	–0.3 V to 30 V
BOOTLO to PGND	–0.3 V to 16 V
BOOT to BOOTLO	–0.3 V to 16 V
IN (see Note 2)	–0.3 V to 16 V
DT (see Note 2)	–0.3 V to 30 V
Continuous total power dissipation	See Dissipation Rating Table
Operating virtual junction temperature range, T_J	–40°C to 125°C
Storage temperature range, T_{stg}	–65°C to 150°C
Lead temperature soldering 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Unless otherwise specified, all voltages are with respect to PGND.
2. High-level input voltages on the IN and DT terminals must be less than or equal to V_{CC} .

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING
D	600 mW	6.0 mW/°C	330 mW	240 mW

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}	4.5		15	V
Input voltage BOOT to PGND	4.5		28	V

electrical characteristics over recommended operating virtual junction temperature range, $V_{CC} = 6.5\text{ V}$, $C_L = 3.3\text{ nF}$ (unless otherwise noted)

supply current

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{CC}	Supply voltage range			4.5		15	V
	Quiescent current	$V_{CC} = 15\text{ V}$				100	μA
		$V_{CC} = 12\text{ V}$, $f_{SWX} = 200\text{ kHz}$, $C_{HIGHDR} = 50\text{ pF}$,	BOOTLO grounded, $C_{LOWDR} = 50\text{ pF}$, See Note 3			3	

NOTE 3: Ensured by design, not production tested.



TPS2832, TPS2833
FAST SYNCHRONOUS-BUCK MOSFET DRIVERS
WITH DEAD-TIME CONTROL

SLVS195C – FEBRUARY 1999 – REVISED JANUARY 2001

electrical characteristics over recommended operating virtual junction temperature range,
 $V_{CC} = 6.5\text{ V}$, $C_L = 3.3\text{ nF}$ (unless otherwise noted) (continued)

output drivers

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT	
Peak output-current	High-side sink (see Note 4)	Duty cycle < 2%, $t_{pw} < 100\ \mu\text{s}$ (see Note 3)	$V_{BOOT} - V_{BOOTLO} = 4.5\text{ V}$, $V_{HIGHDR} = 4\text{ V}$	0.7	1.1		A	
			$V_{BOOT} - V_{BOOTLO} = 6.5\text{ V}$, $V_{HIGHDR} = 5\text{ V}$	1.1	1.5			
			$V_{BOOT} - V_{BOOTLO} = 12\text{ V}$, $V_{HIGHDR} = 10.5\text{ V}$	2	2.4			
	High-side source (see Note 4)	Duty cycle < 2%, $t_{pw} < 100\ \mu\text{s}$ (see Note 3)	$V_{BOOT} - V_{BOOTLO} = 4.5\text{ V}$, $V_{HIGHDR} = 0.5\text{ V}$	1.2	1.4		A	
			$V_{BOOT} - V_{BOOTLO} = 6.5\text{ V}$, $V_{HIGHDR} = 1.5\text{ V}$	1.3	1.6			
			$V_{BOOT} - V_{BOOTLO} = 12\text{ V}$, $V_{HIGHDR} = 1.5\text{ V}$	2.3	2.7			
	Low-side sink (see Note 4)	Duty cycle < 2%, $t_{pw} < 100\ \mu\text{s}$ (see Note 3)	$V_{CC} = 4.5\text{ V}$, $V_{LOWDR} = 4\text{ V}$	1.3	1.8		A	
			$V_{CC} = 6.5\text{ V}$, $V_{LOWDR} = 5\text{ V}$	2	2.5			
			$V_{CC} = 12\text{ V}$, $V_{LOWDR} = 10.5\text{ V}$	3	3.5			
	Low-side source (see Note 4)	Duty cycle < 2%, $t_{pw} < 100\ \mu\text{s}$ (see Note 3)	$V_{CC} = 4.5\text{ V}$, $V_{LOWDR} = 0.5\text{ V}$	1.4	1.7		A	
			$V_{CC} = 6.5\text{ V}$, $V_{LOWDR} = 1.5\text{ V}$	2	2.4			
			$V_{CC} = 12\text{ V}$, $V_{LOWDR} = 1.5\text{ V}$	2.5	3			
Output resistance	High-side sink (see Note 4)		$V_{BOOT} - V_{BOOTLO} = 4.5\text{ V}$, $V_{HIGHDR} = 0.5\text{ V}$			5	Ω	
			$V_{BOOT} - V_{BOOTLO} = 6.5\text{ V}$, $V_{HIGHDR} = 0.5\text{ V}$			5		
			$V_{BOOT} - V_{BOOTLO} = 12\text{ V}$, $V_{HIGHDR} = 0.5\text{ V}$			5		
	High-side source (see Note 4)			$V_{BOOT} - V_{BOOTLO} = 4.5\text{ V}$, $V_{HIGHDR} = 4\text{ V}$			75	Ω
				$V_{BOOT} - V_{BOOTLO} = 6.5\text{ V}$, $V_{HIGHDR} = 6\text{ V}$			75	
				$V_{BOOT} - V_{BOOTLO} = 12\text{ V}$, $V_{HIGHDR} = 11.5\text{ V}$			75	
	Low-side sink (see Note 4)			$V_{DRV} = 4.5\text{ V}$, $V_{LOWDR} = 0.5\text{ V}$			9	Ω
				$V_{DRV} = 6.5\text{ V}$, $V_{LOWDR} = 0.5\text{ V}$			7.5	
				$V_{DRV} = 12\text{ V}$, $V_{LOWDR} = 0.5\text{ V}$			6	
	Low-side source (see Note 4)			$V_{DRV} = 4.5\text{ V}$, $V_{LOWDR} = 4\text{ V}$			75	Ω
				$V_{DRV} = 6.5\text{ V}$, $V_{LOWDR} = 6\text{ V}$			75	
				$V_{DRV} = 12\text{ V}$, $V_{LOWDR} = 11.5\text{ V}$			75	

NOTES: 3. Ensured by design, not production tested.

4. The pull-up/pull-down circuits of the drivers are bipolar and MOSFET transistors in parallel. The peak output current rating is the combined current from the bipolar and MOSFET transistors. The output resistance is the $R_{ds(on)}$ of the MOSFET transistor when the voltage on the driver output is less than the saturation voltage of the bipolar transistor.

dead time

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{IH}	High-level input voltage	LOWDR Over the V_{CC} range (see Note 3)	0.7 V_{CC}			V
V_{IL}	Low-level input voltage		1			
V_{IH}	High-level input voltage	DT Over the V_{CC} range	0.7 V_{CC}			V
V_{IL}	Low-level input voltage		1			

NOTE 3: Ensured by design, not production tested.

digital control terminals

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{IH}	High-level input voltage	Over the V_{CC} range	0.7 V_{CC}			V
V_{IL}	Low-level input voltage		1			V



TPS2832, TPS2833
FAST SYNCHRONOUS-BUCK MOSFET DRIVERS
WITH DEAD-TIME CONTROL

SLVS195C – FEBRUARY 1999 – REVISED JANUARY 2001

**switching characteristics over recommended operating virtual junction temperature range,
 $C_L = 3.3 \text{ nF}$ (unless otherwise noted)**

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Rise time	HIGHDR output (see Note 3)	$V_{BOOT} = 4.5 \text{ V}, V_{BOOTLO} = 0 \text{ V}$			60	ns
		$V_{BOOT} = 6.5 \text{ V}, V_{BOOTLO} = 0 \text{ V}$			50	
		$V_{BOOT} = 12 \text{ V}, V_{BOOTLO} = 0 \text{ V}$			50	
	LOWDR output (see Note 3)	$V_{CC} = 4.5 \text{ V}$			40	ns
		$V_{CC} = 6.5 \text{ V}$			30	
		$V_{CC} = 12 \text{ V}$			30	
Fall time	HIGHDR output (see Note 3)	$V_{BOOT} = 4.5 \text{ V}, V_{BOOTLO} = 0 \text{ V}$			60	ns
		$V_{BOOT} = 6.5 \text{ V}, V_{BOOTLO} = 0 \text{ V}$			50	
		$V_{BOOT} = 12 \text{ V}, V_{BOOTLO} = 0 \text{ V}$			50	
	LOWDR output (see Note 3)	$V_{CC} = 4.5 \text{ V}$			40	ns
		$V_{CC} = 6.5 \text{ V}$			30	
		$V_{CC} = 12 \text{ V}$			30	
Propagation delay time	HIGHDR going low (excluding dead time) (see Note 3)	$V_{BOOT} = 4.5 \text{ V}, V_{BOOTLO} = 0 \text{ V}$			130	ns
		$V_{BOOT} = 6.5 \text{ V}, V_{BOOTLO} = 0 \text{ V}$			100	
		$V_{BOOT} = 12 \text{ V}, V_{BOOTLO} = 0 \text{ V}$			75	
	LOWDR going high (excluding dead time) (see Note 3)	$V_{BOOT} = 4.5 \text{ V}, V_{BOOTLO} = 0 \text{ V}$			80	ns
		$V_{BOOT} = 6.5 \text{ V}, V_{BOOTLO} = 0 \text{ V}$			70	
		$V_{BOOT} = 12 \text{ V}, V_{BOOTLO} = 0 \text{ V}$			60	
Propagation delay time	LOWDR going low (excluding dead time) (see Note 3)	$V_{CC} = 4.5 \text{ V}$			80	ns
		$V_{CC} = 6.5 \text{ V}$			70	
		$V_{CC} = 12 \text{ V}$			60	
Driver nonoverlap time	DT to LOWDR and LOWDR to HIGHDR (see Note 3)	$V_{CC} = 4.5 \text{ V}$	40		170	ns
		$V_{CC} = 6.5 \text{ V}$	25		135	
		$V_{CC} = 12 \text{ V}$	15		85	

NOTE 3: Ensured by design, not production tested.



TPS2832, TPS2833
FAST SYNCHRONOUS-BUCK MOSFET DRIVERS
WITH DEAD-TIME CONTROL

SLVS195C – FEBRUARY 1999 – REVISED JANUARY 2001

TYPICAL CHARACTERISTICS

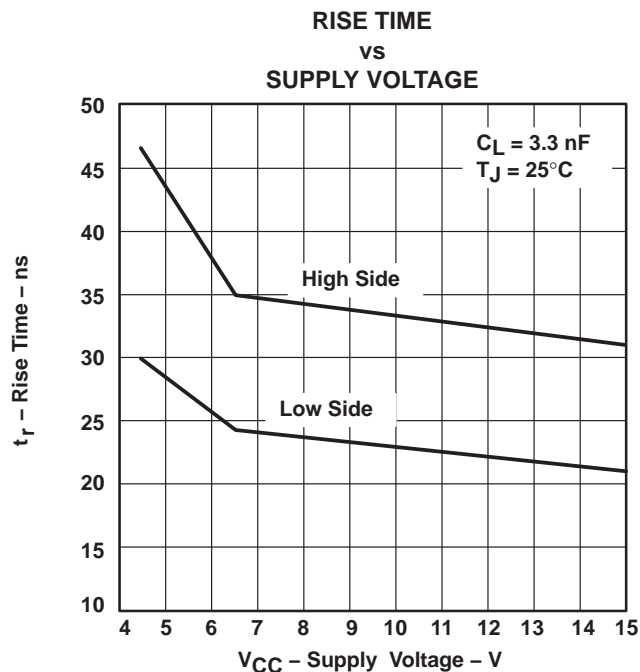


Figure 1

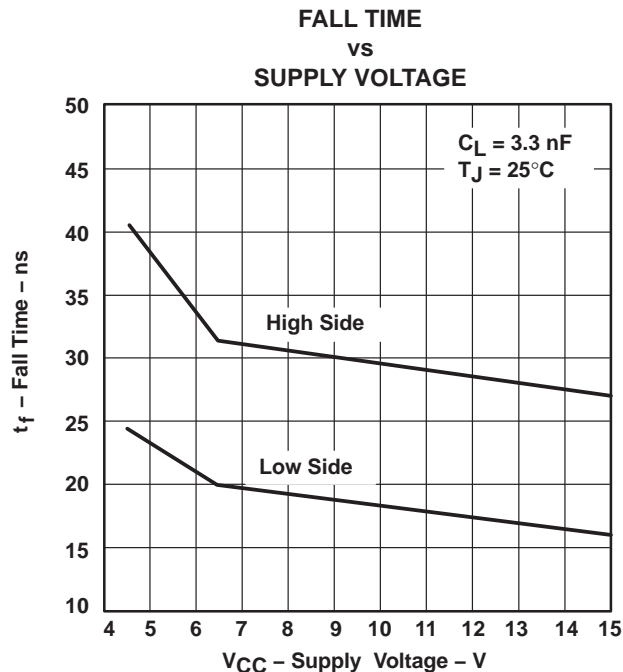


Figure 2

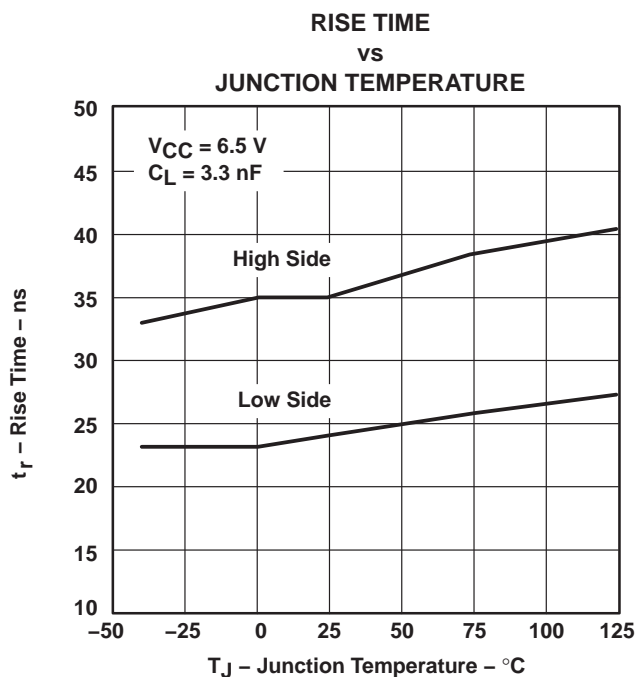


Figure 3

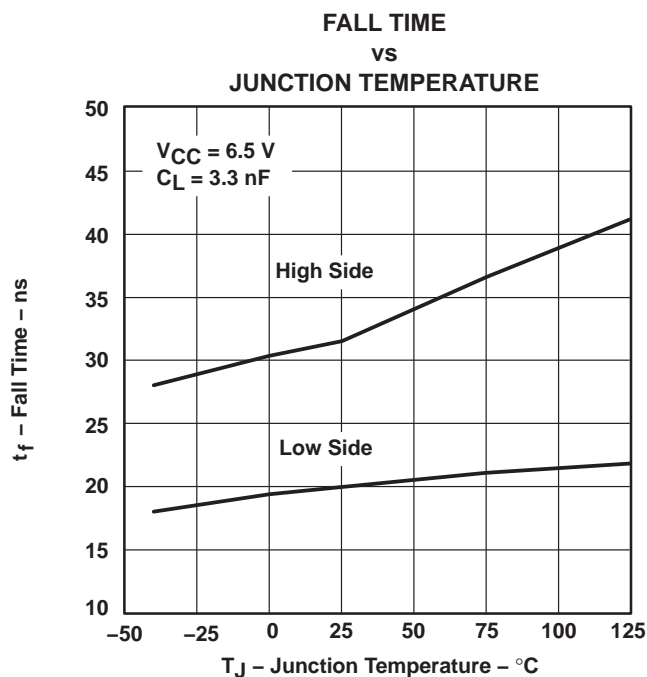


Figure 4

TPS2832, TPS2833
FAST SYNCHRONOUS-BUCK MOSFET DRIVERS
WITH DEAD-TIME CONTROL

SLVS195C – FEBRUARY 1999 – REVISED JANUARY 2001

TYPICAL CHARACTERISTICS

LOW-TO-HIGH PROPAGATION DELAY TIME
vs
SUPPLY VOLTAGE, LOW TO HIGH LEVEL

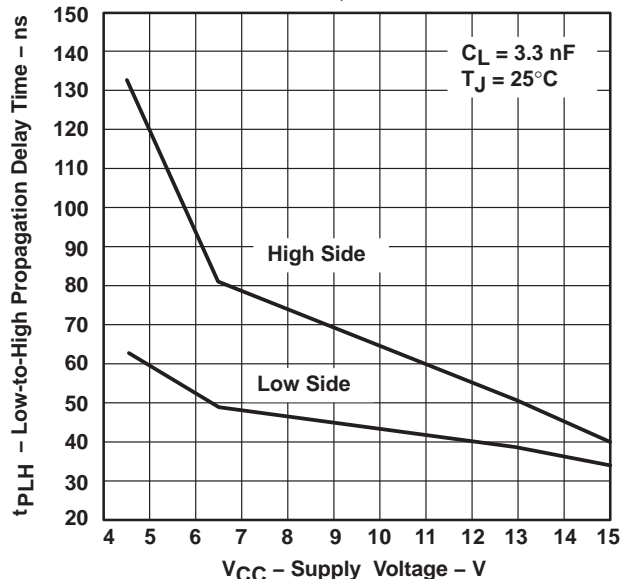


Figure 5

HIGH-TO-LOW PROPAGATION DELAY TIME
vs
SUPPLY VOLTAGE, HIGH TO LOW LEVEL

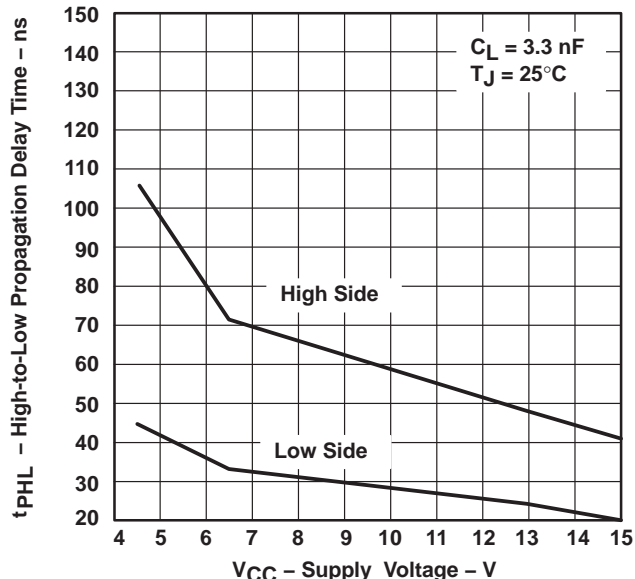


Figure 6

LOW-TO-HIGH PROPAGATION DELAY TIME
vs
JUNCTION TEMPERATURE

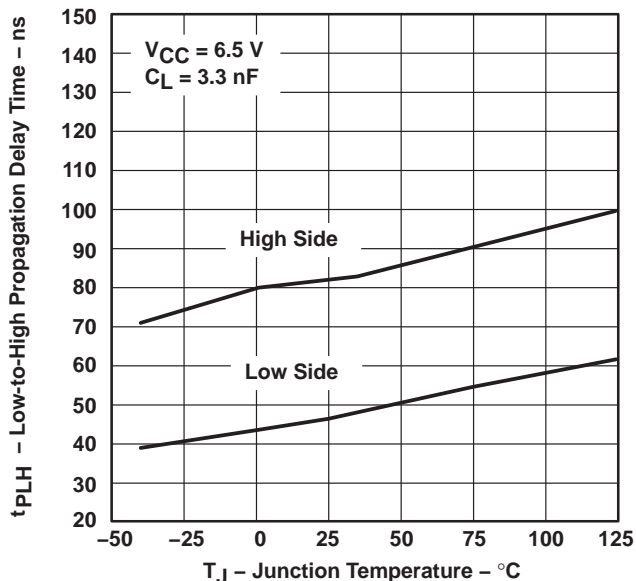


Figure 7

HIGH-TO-LOW PROPAGATION DELAY TIME
vs
JUNCTION TEMPERATURE

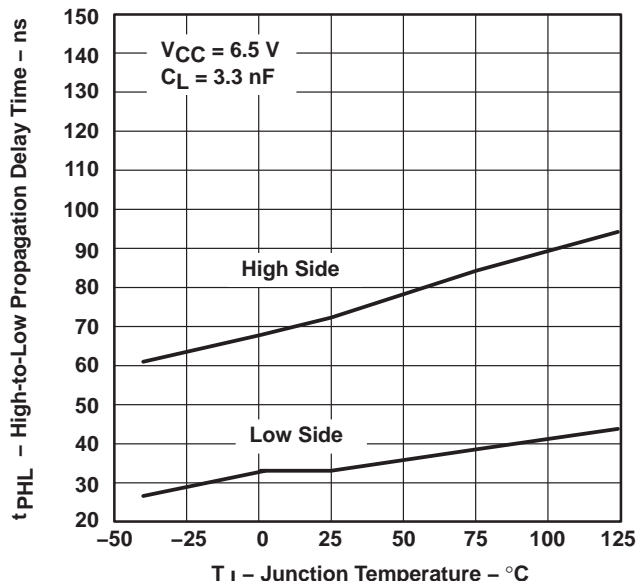


Figure 8



TYPICAL CHARACTERISTICS

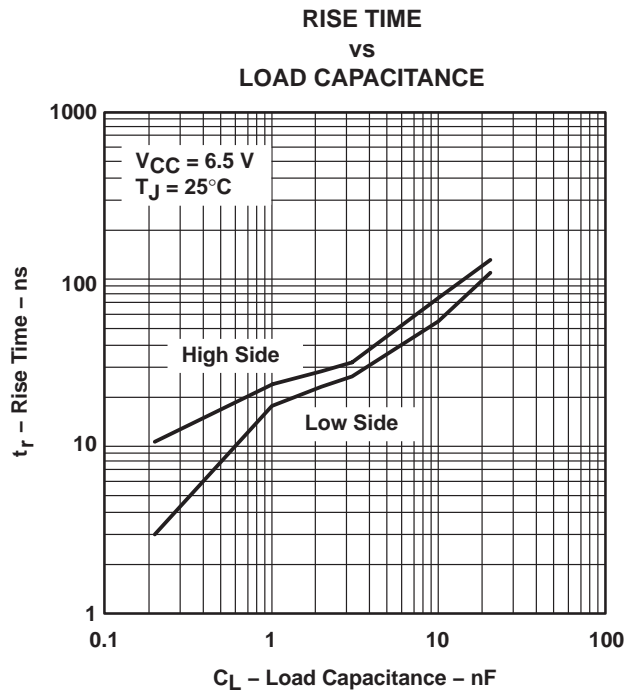


Figure 9

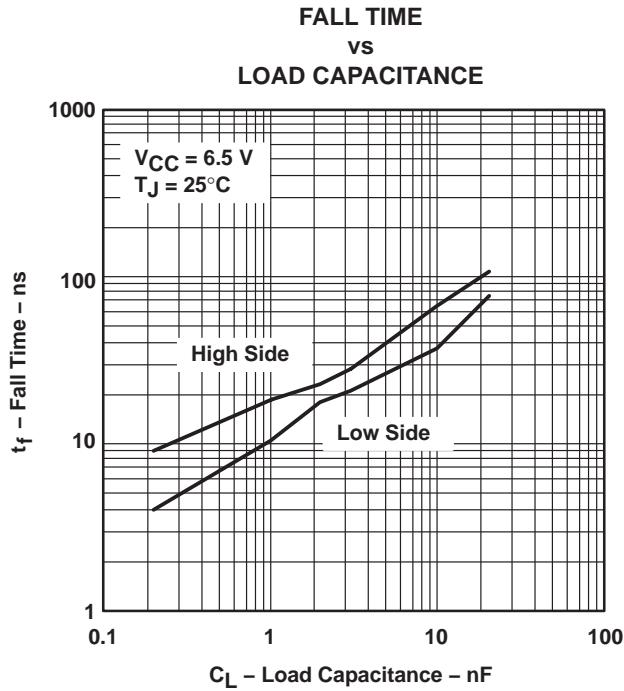


Figure 10

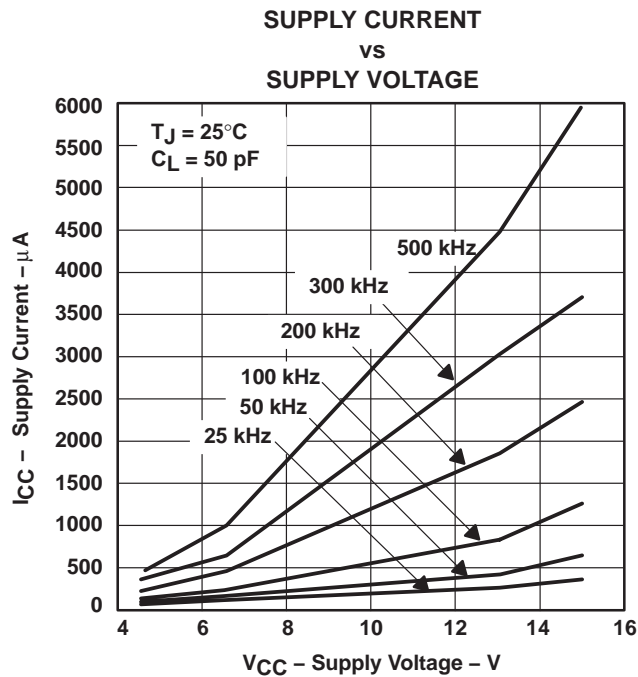


Figure 11

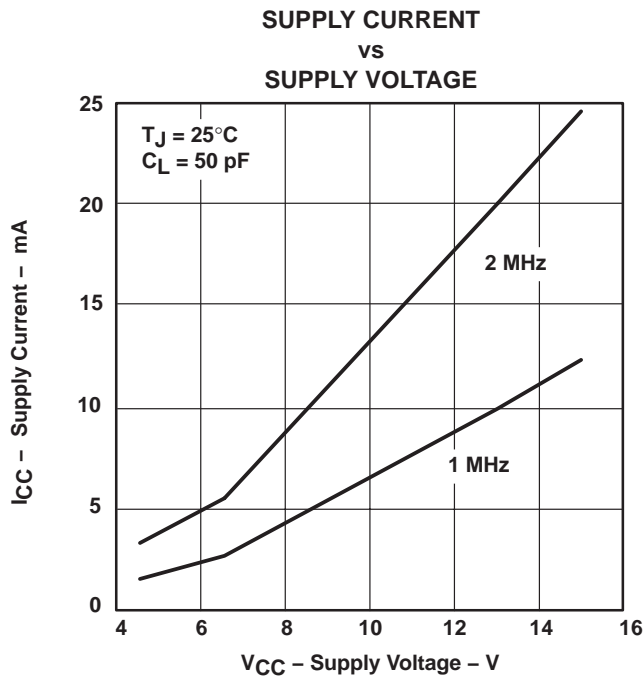


Figure 12

TPS2832, TPS2833
FAST SYNCHRONOUS-BUCK MOSFET DRIVERS
WITH DEAD-TIME CONTROL

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TYPICAL CHARACTERISTICS

PEAK SOURCE CURRENT
vs
SUPPLY VOLTAGE

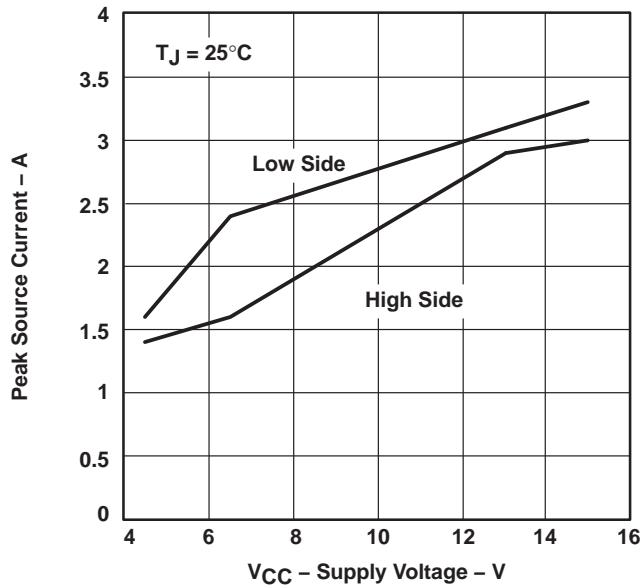


Figure 13

PEAK SINK CURRENT
vs
SUPPLY VOLTAGE

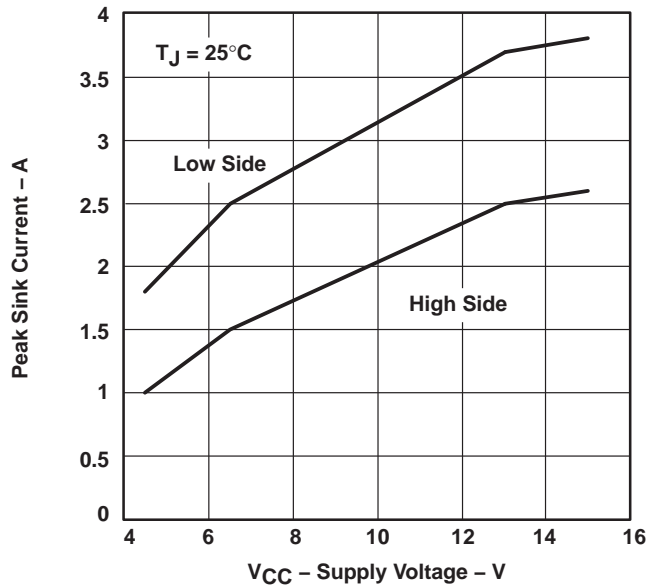


Figure 14

INPUT THRESHOLD VOLTAGE
vs
SUPPLY VOLTAGE

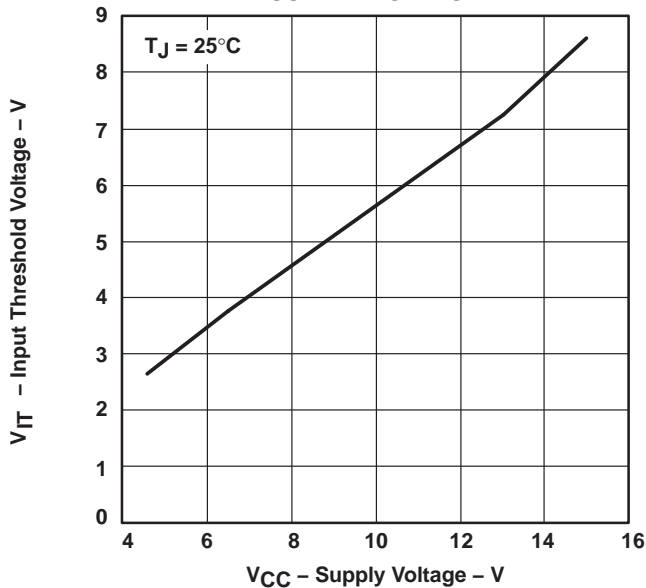


Figure 15



TPS2832, TPS2833 FAST SYNCHRONOUS-BUCK MOSFET DRIVERS WITH DEAD-TIME CONTROL

SLVS195C – FEBRUARY 1999 – REVISED JANUARY 2001

APPLICATION INFORMATION

Great care should be taken when laying out the pc board. The power-processing section is the most critical and will generate large amounts of EMI if not properly configured. The junction of Q1, Q2, and L1 should be very tight. The connection from Q1 drain to the positive sides of C5, C10, and C11 and the connection from Q2 source to the negative sides of C5, C10, and C11 should be as short as possible. The negative terminals of C7 and C12 should also be connected to Q2 source.

Next, the traces from the MOSFET driver to the power switches should be considered. The BOOTLO signal from the junction of Q1 and Q2 carries the large gate drive current pulses and should be as heavy as the gate drive traces. The bypass capacitor (C14) should be tied directly across V_{CC} and PGND.

The next most sensitive node is the FB node on the controller (terminal 4 on the TL5001A) This node is very sensitive to noise pickup and should be isolated from the high-current power stage and be as short as possible. The ground around the controller and low-level circuitry should be tied to the power ground as the output. If these three areas are properly laid out, the rest of the circuit should not have any other EMI problems and the power supply will be relatively free of noise.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS2832D	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	-40 to 125	2832
TPS2832DR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2832
TPS2832DR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2832
TPS2833D	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2833
TPS2833D.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2833

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS2832DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS2832DR	SOIC	D	8	2500	340.5	338.1	20.6

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TPS2833D	D	SOIC	8	75	507	8	3940	4.32
TPS2833D.A	D	SOIC	8	75	507	8	3940	4.32

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